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5-15-01 34
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Yoshihisa FURUTA, et al.

Appln. No.: 09/719,422

Group Art Unit: 1734

Confirmation No.: NOT YET ASSIGNED

Examiner: NOT YET ASSIGNED

Filed: December 12, 2000

For: METHOD OF RESIN ENCAPSULATING SEMICONDUCTOR CHIP AND
PRESSURE-SENSITIVE ADHESIVE TAPE FOR ADHESION TO LEADFRAME
AND THE LIKE

SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents
Washington, D.C. 20231

Sir:

Submitted herewith please find 2 sheets of formal drawings (Figs. 1-3). The Examiner is respectfully requested to acknowledge receipt of these formal drawings.

Respectfully submitted,



Mark Boland
Registration No. 32,197

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Date: March 19, 2001

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